



**P.E.S. College of Engineering, Mandya - 571 401**

*(An Autonomous Institution affiliated to VTU, Belagavi)*

**Eighth Semester, B.E. - Electronics and Communication Engineering**

**Semester End Examination; May/June - 2018**

**ASIC Design**

Time: 3 hrs

Max. Marks: 100

*Note: Answer FIVE full questions, selecting ONE full question from each unit.*

**UNIT - I**

- 1 a. What are the sequences of steps used to design an ASIC? Draw the flow diagram for the ASIC design. Also, comment on logical and physical design. 12
- b. Analyze the advantages and disadvantages with the use of FPGA and full custom ASIC. 8
- 2 a. Explain how Carry Save Adder (CSA) reduces carry rippling in addition. How are 4-bit CSA constructed using 3-bit CSA? What is the need for inserting latches in the 4-bit CSA? 8
- b. What does each ASIC cell contain when ASIC cell libraries are designed? Explain each of them in detail. 10
- c. Define ASIC and give two example for non-ASIC and ASICs. 2

**UNIT - II**

- 3 a. Analyze the working of three-state bidirectional output buffer. A device has 33 input/output (I/O) cells each drawing 30 mA while switching. If all the I/O cells switch simultaneously, what will be the power-supply bounce, if current changes from 0 to 1 A in 5 ns and power-supply inductance are 2 nH? 8
- b. Recode the unsigned Binary number B = 00010111 as CSD vector D. 5
- c. Consider 2X drive NOR3 logic cell in C<sub>5</sub> technology with each input driven with a 1X inverter, compute the delay. Given logic ratio r = 1.5 and C<sub>out</sub> = 0.3 pF. 7
- 4 a. Determine the optimum path delay for the logic cascade chain shown in Fig. Q 4(a). Also, compute the input capacitance C<sub>2</sub>, C<sub>3</sub> and C<sub>4</sub>. Ignore p and q of each stage. Assume logical ratio, r = 2, C<sub>1</sub> = 1 pF. 10

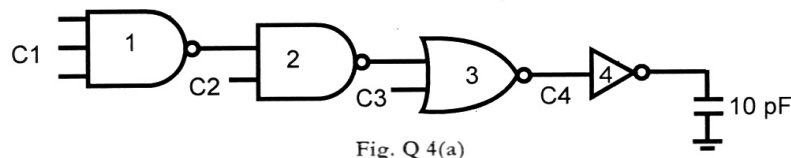


Fig. Q 4(a)

- b. For a cascaded chain of N inverters each with equal stage effort, compute the value of stage electrical effort for minimum delay. 5
- c. For a CMOS AOI221 logic cell shown in Fig. Q 4(c), compute logical effort and logical area for logic ratio, r = 2 5

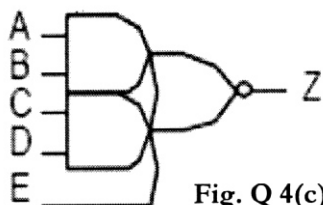


Fig. Q 4(c)

**UNIT - III**

- 5a. What is the need for hierarchical design? With suitable example, explain the hierarchical design. Also, explain how to label the nets in the hierarchical design. 10
- b. What is netlist screener? List the errors that can be found by it. 5
- c. What is logic synthesis? What are ways of optimization performed during logic synthesis? Explain them. 5
- 6a. Explain the basic structure of CFI 1.0.0 base connectivity model. 8
- b. Analyze various types of simulation performed in ASIC design flow. 6
- c. What is EDIF? Write the hierarchical nature of an EDIF file and explain. 6

**UNIT - IV**

- 7a. What is the need of methods and algorithms in CAD tool designing? Discuss the types of algorithms/functions used to reduce complexity. 8
- b. Mention the steps used in constructive partitioning algorithm. 6
- c. An ASIC chip has 40000 Flips-flops with input capacitance of clock input to each Flip-flop is 0.025 pF with clock frequency of 200 MHz, chip size of 20 mm on a side and clock spine consists of 200 lines across the chip with interconnect capacitance of 2 pF/cm and  $V_{dd}$  of 3.3 V, calculate; 6
  - i) Number of stages to drive the clock spine
  - ii) Power dissipated while charging the input capacitance of Flip-flop
  - iii) Power dissipated while driving clock spine
  - iv) Peak current if rise time is 0.1 ns
- 8a. What are the various iterative placement improvement algorithms used to improve the existing placement solutions? Explain with examples to each. 10
- b. What is slicing in floor-planning? Illustrate with an example. What are cyclic constraints? How do you resolve them? 7
- c. Why the stem of a T-junction has to be routed first? Explain with example. 3

**UNIT - V**

- 9a. What is the sequence of steps used in timing-driven floor planning and placement design (physical design flow)? With the help of flow diagram explain each step. 10
- b. Find the global channel density for the channel shown in Fig. Q 9(b). 2

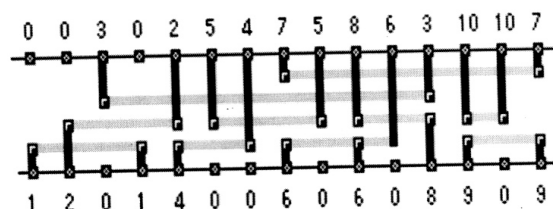


Fig. Q 9 (b)

- c. Explain global routing between the blocks and inside the flexible blocks. 8
- 10a. Illustrate with an example Lee-maze-running algorithm. 5
- b. Demonstrate the left-edge algorithm with an example. List all the steps. 8
- c. What is circuit extraction? Illustrate the various formats in which the parasitic information is passed back. 7